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# United States Patent [19]

Takagi et al.

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[54] SEMICONDUCTOR ELEMENT MODULE AND SEMICONDUCTOR DEVICE WHICH PREVENTS SHORT CIRCUITING

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[57] ABSTRACT

A semiconductor element module includes a package, a semiconductor element arranged on the package, and a plurality of leads provided on sides of the package so that an opening end of each lead is oriented to the side of a package attaching plane, and serving to connect the semiconductor element to an external circuit; wherein a level differences is provided on the side of the package attaching plane of each of package sides so that a space is formed from each the plurality of leads.

10 Claims, 6 Drawing Sheets

